



US00D442568S

(12) **United States Design Patent**
Masuo et al.

(10) **Patent No.:** **US D442,568 S**
(45) **Date of Patent:** **** May 22, 2001**

(54) **IC MODULE INSERT**

(75) Inventors: **Yoshiyuki Masuo; Toshiyuki Kiyokawa; Hiroyuki Takahashi**, all of Tokyo (JP)

(73) Assignee: **advantest Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/120,362**

(22) Filed: **Mar. 20, 2000**

(30) **Foreign Application Priority Data**

Sep. 20, 1999 (JP) 11-24949
Sep. 20, 1999 (JP) 11-24950

(51) **LOC (7) Cl.** **13-99**

(52) **U.S. Cl.** **D13/199; D13/182**

(58) **Field of Search** **D13/182, 199; 211/41.17, 162**

(56) **References Cited**

U.S. PATENT DOCUMENTS

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Primary Examiner—Brian N. Vinson
(74) *Attorney, Agent, or Firm*—Birch, Stewart, Kolasch & Birch, LLP

(57) **CLAIM**

The ornamental design for an IC module insert, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an IC module insert according to a first embodiment of the present design.
FIG. 2 is a front view of the IC module insert shown in FIG. 1.
FIG. 3 is a rear view of the IC module insert shown in FIG. 1.
FIG. 4 is a left side view of the IC module insert shown in FIG. 1.
FIG. 5 is a right side view of the IC module insert shown in FIG. 1.
FIG. 6 is a top plan view of the IC module insert shown in FIG. 1.
FIG. 7 is a bottom plan view of the IC module insert shown in FIG. 1.
FIG. 8 is a sectional view along line VIII—VIII of FIG. 2.
FIG. 9 is a sectional view along line IX—IX of FIG. 6.
FIG. 10 is a perspective view of an IC module insert according to a second embodiment of the present design.
FIG. 11 is a front view of the IC module insert shown in FIG. 10.
FIG. 12 is a rear view of the IC module insert shown in FIG. 10.
FIG. 13 is a left side view of the IC module insert shown in FIG. 10.
FIG. 14 is a right side view of the IC module insert shown in FIG. 10.
FIG. 15 is a top plan view of the IC module insert shown in FIG. 10.
FIG. 16 is a bottom plan view of the IC module insert shown in FIG. 10.
FIG. 17 is a sectional view along line XVII—XVII of FIG. 11.
FIG. 18 is a sectional view along line XVIII—XVIII of FIG. 15; and,
FIG. 19 is a reduced perspective view of the embodiment of FIG. 1, with the broken-line disclosure of a second module insert and the larger rack assembly being for illustrative purposes only and forming no part of the claimed design.

1 Claim, 7 Drawing Sheets

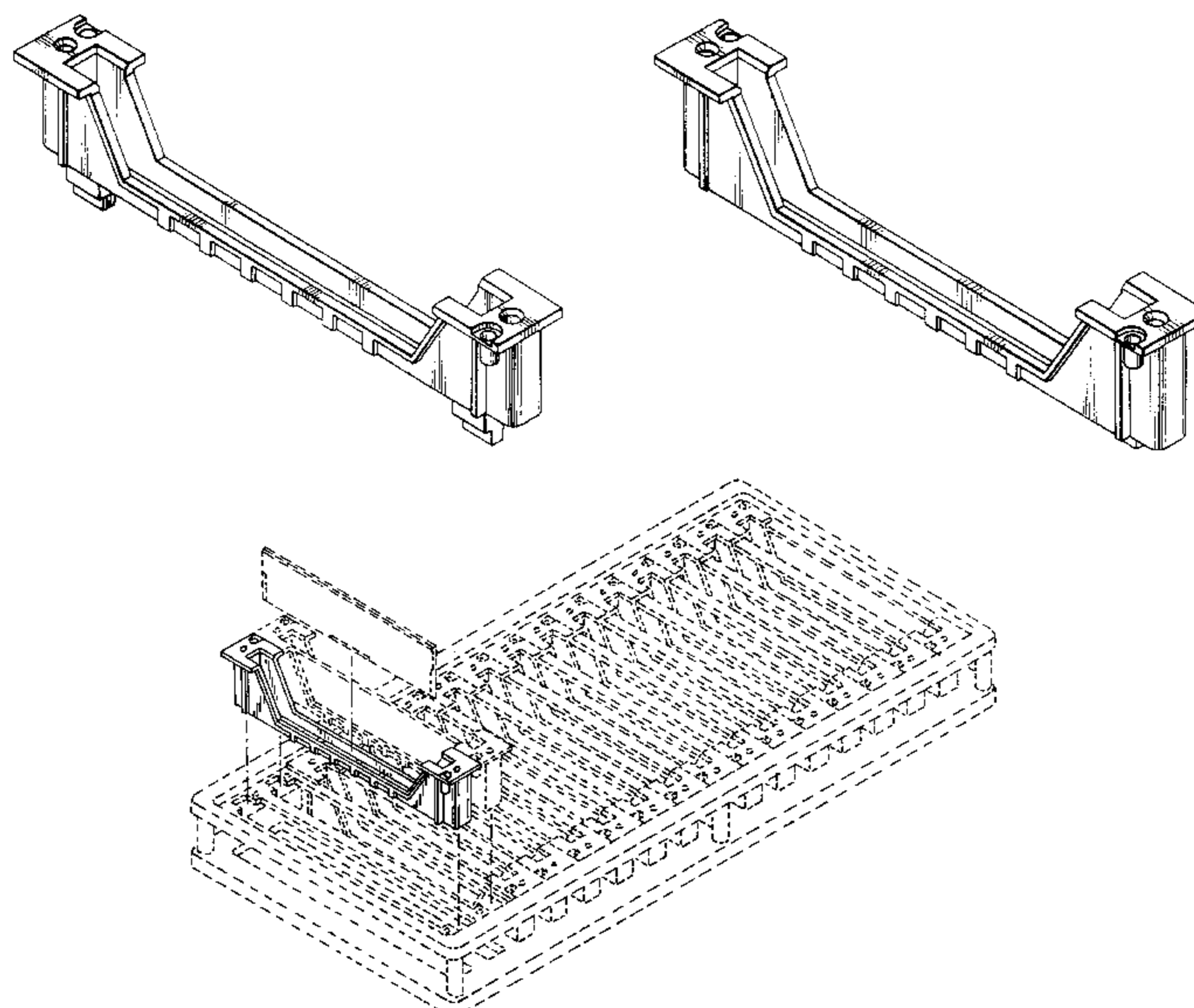


FIG. 1

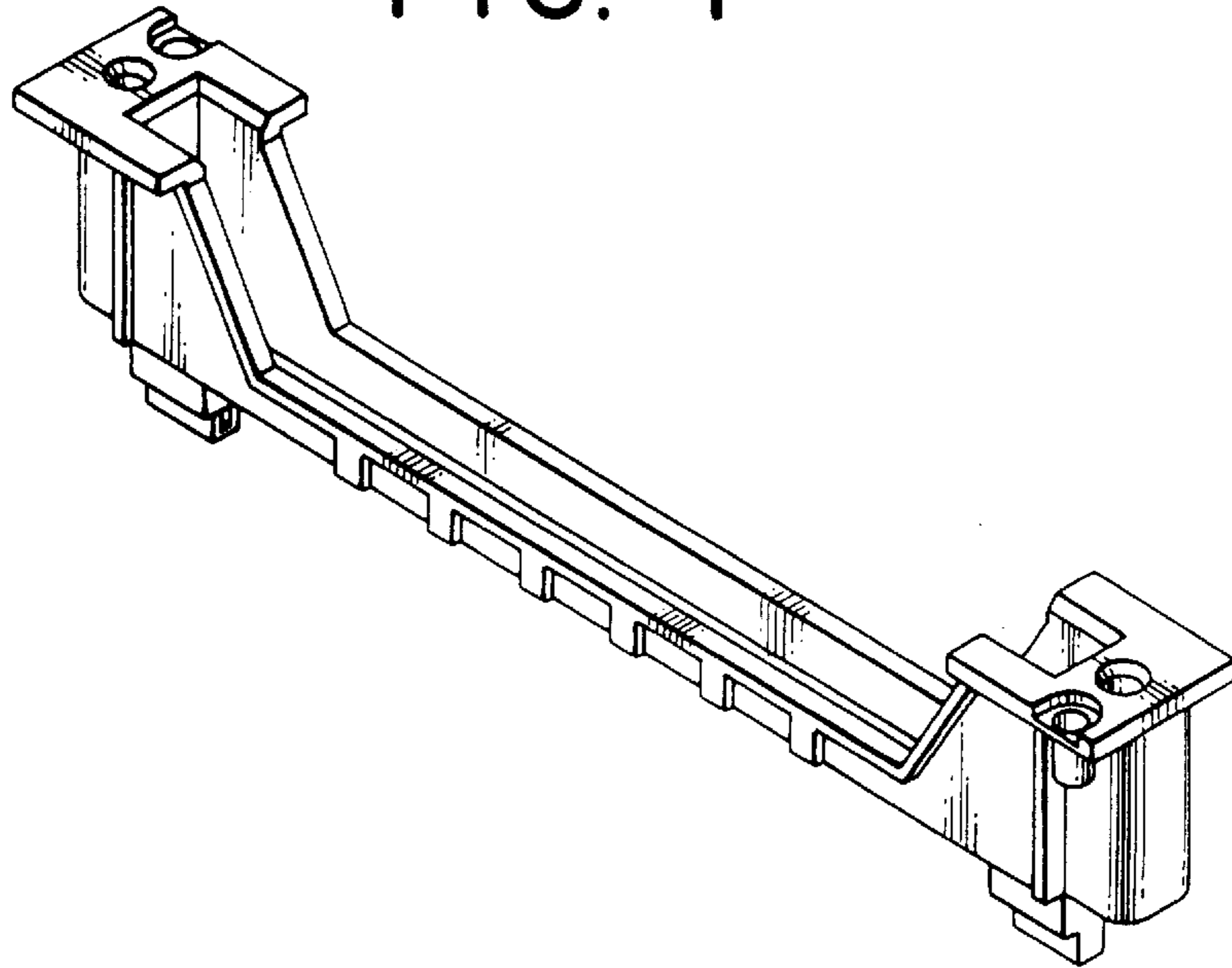


FIG. 2

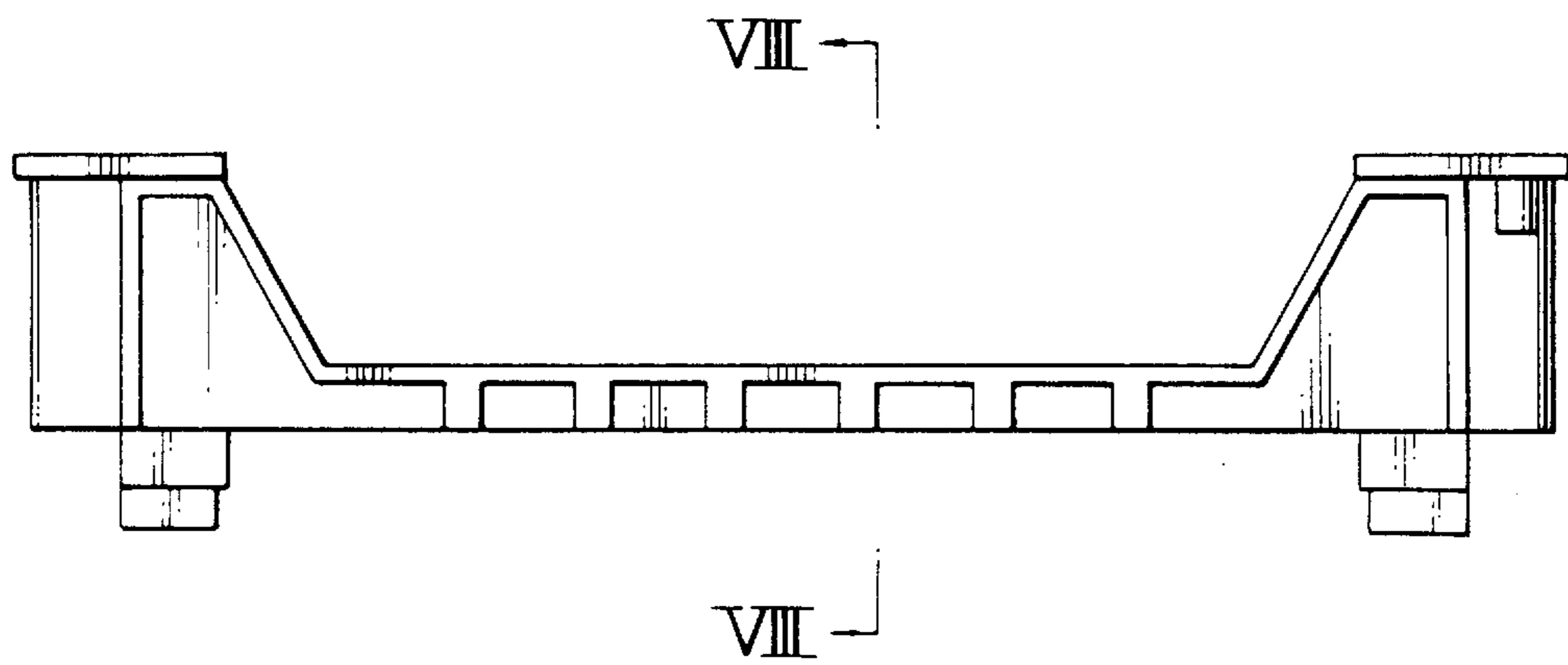


FIG. 3

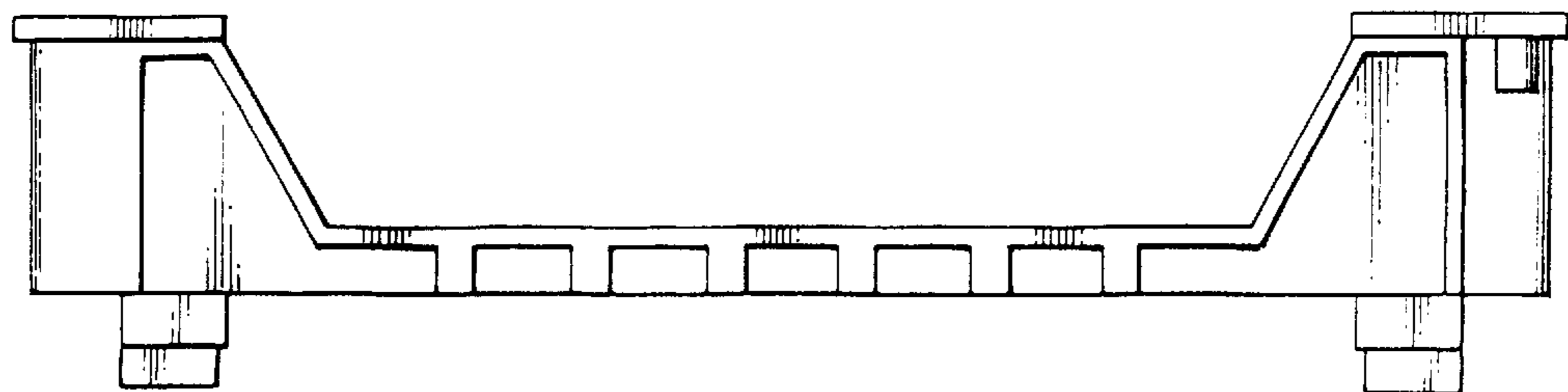


FIG. 4

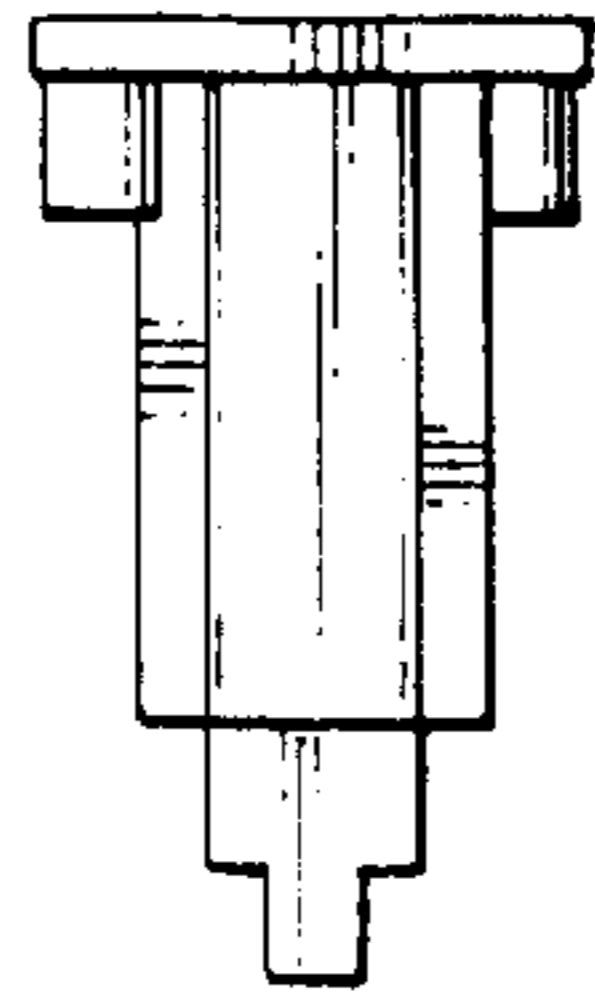


FIG. 5

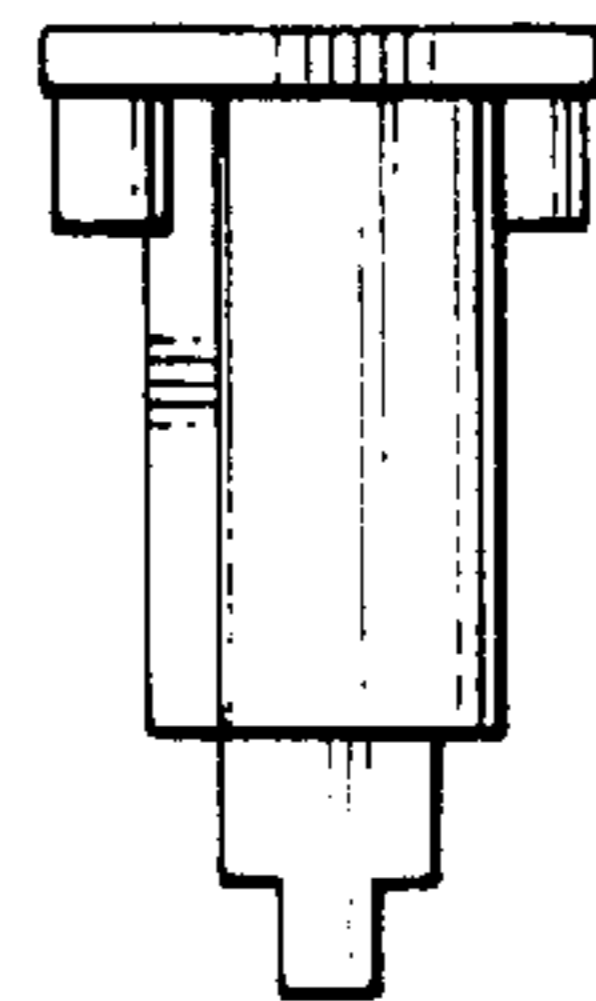


FIG. 6

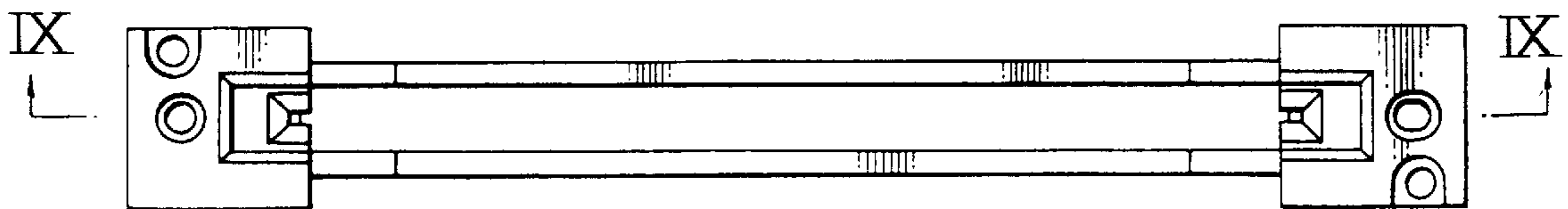


FIG. 7

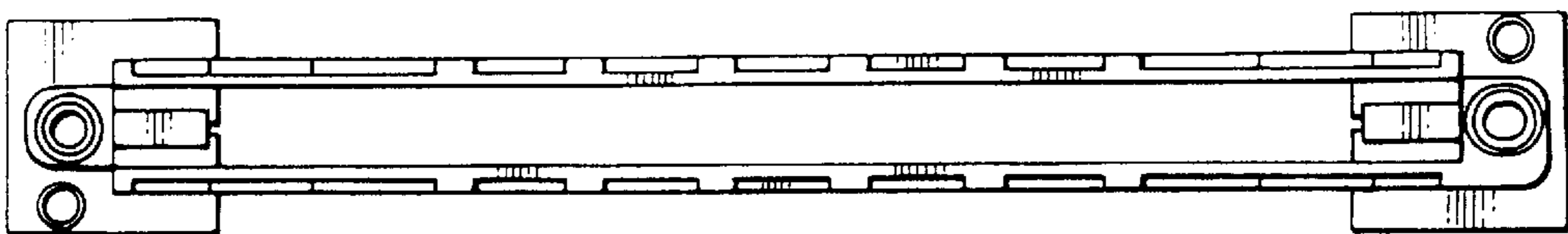


FIG. 8

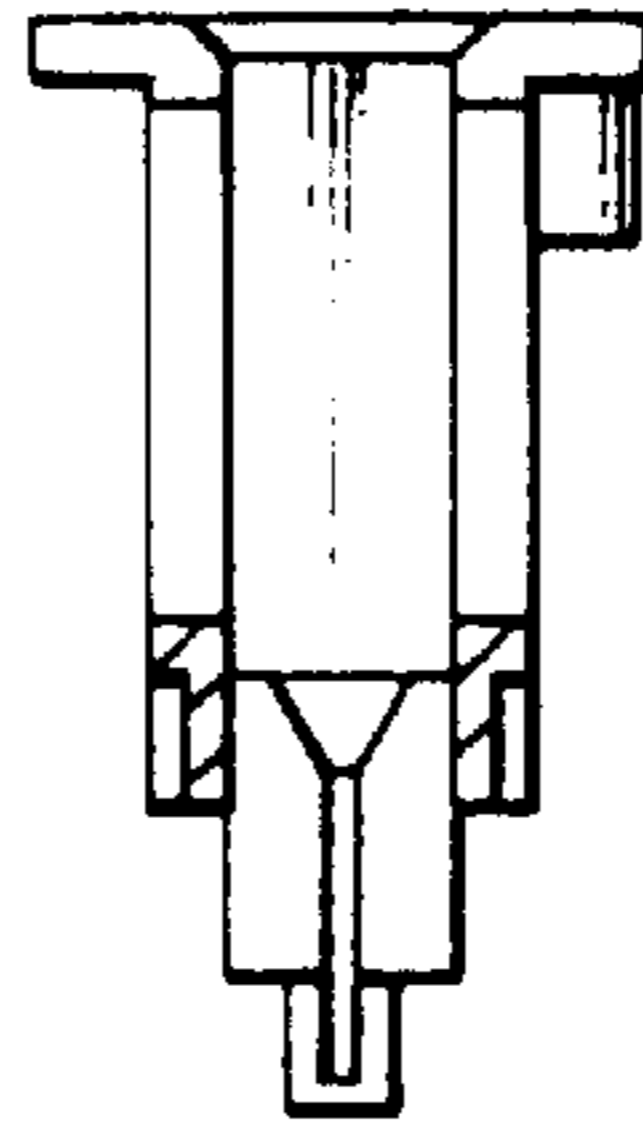


FIG. 9

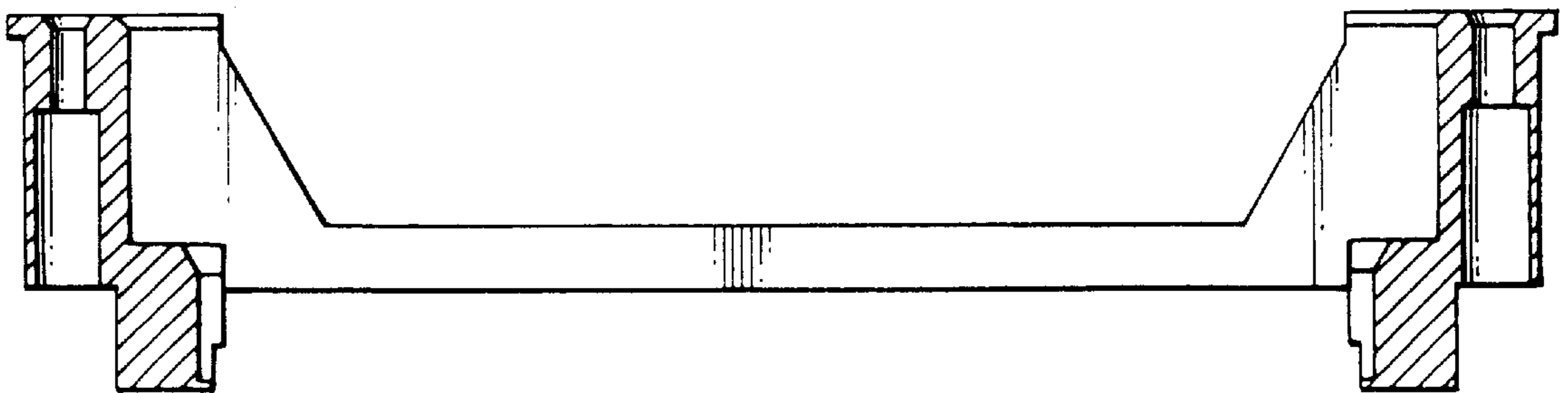


FIG. 10

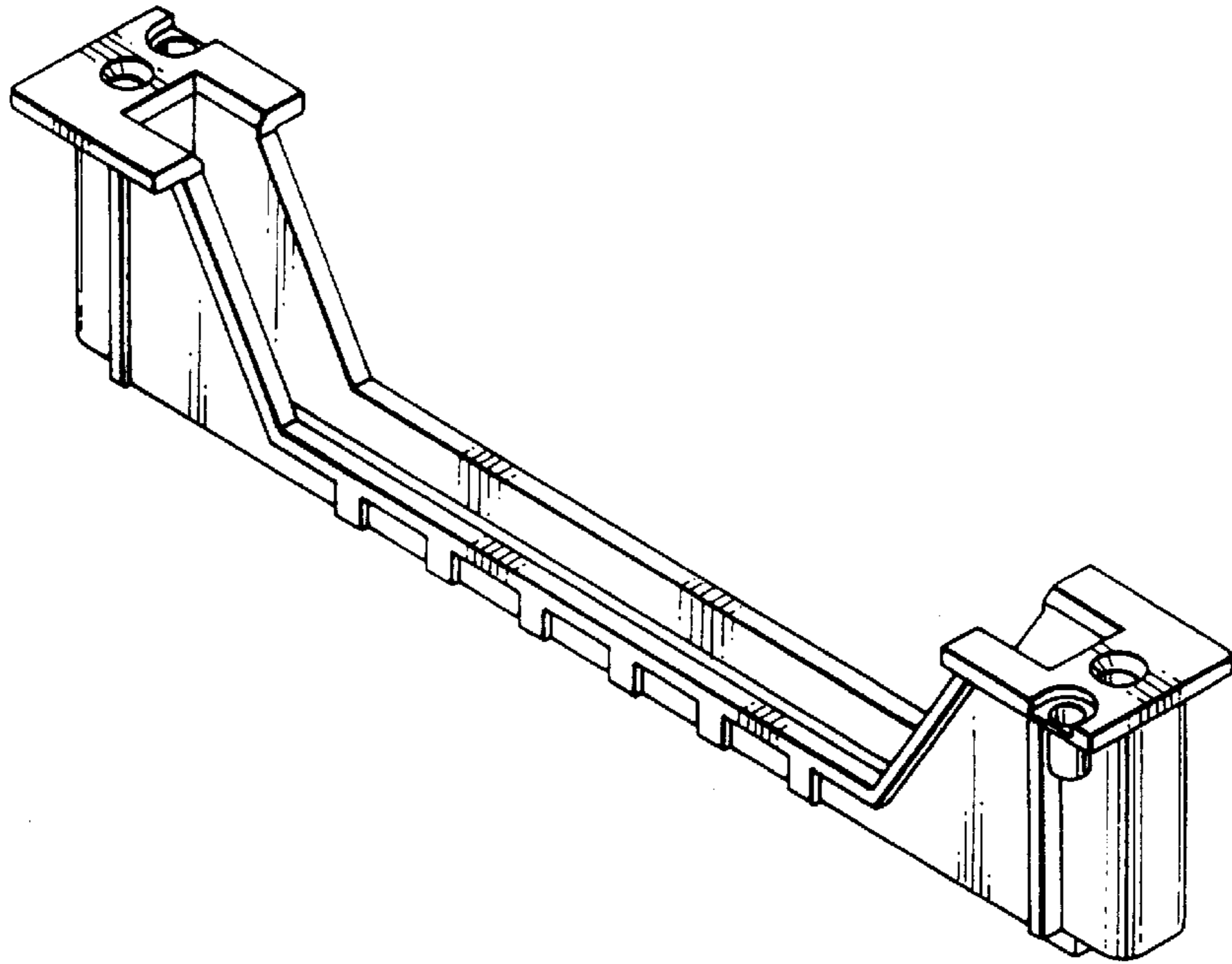
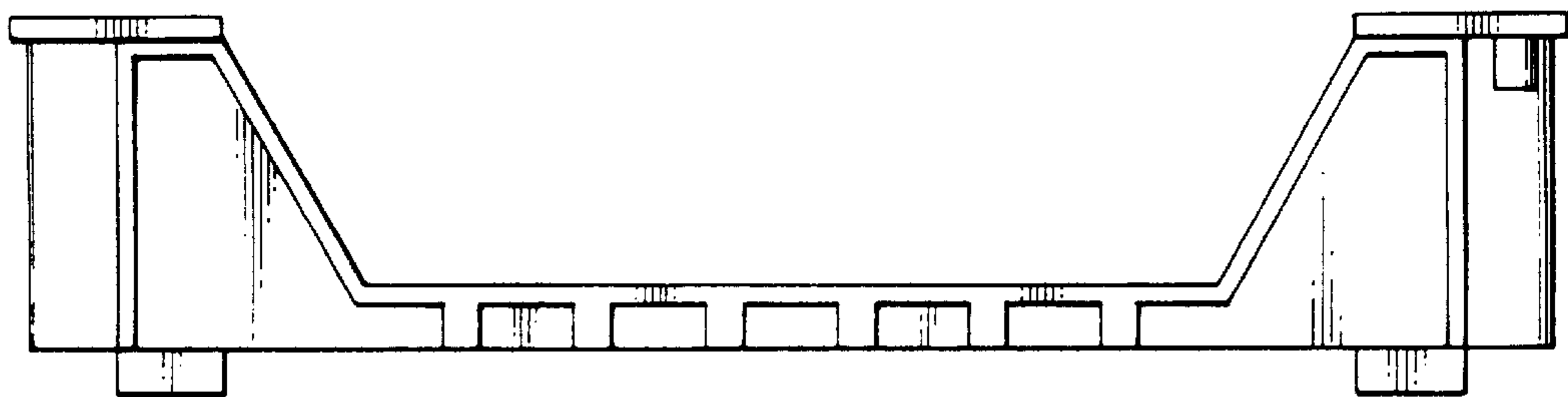


FIG. 11

XVII ↙



XVII ↘

FIG. 12

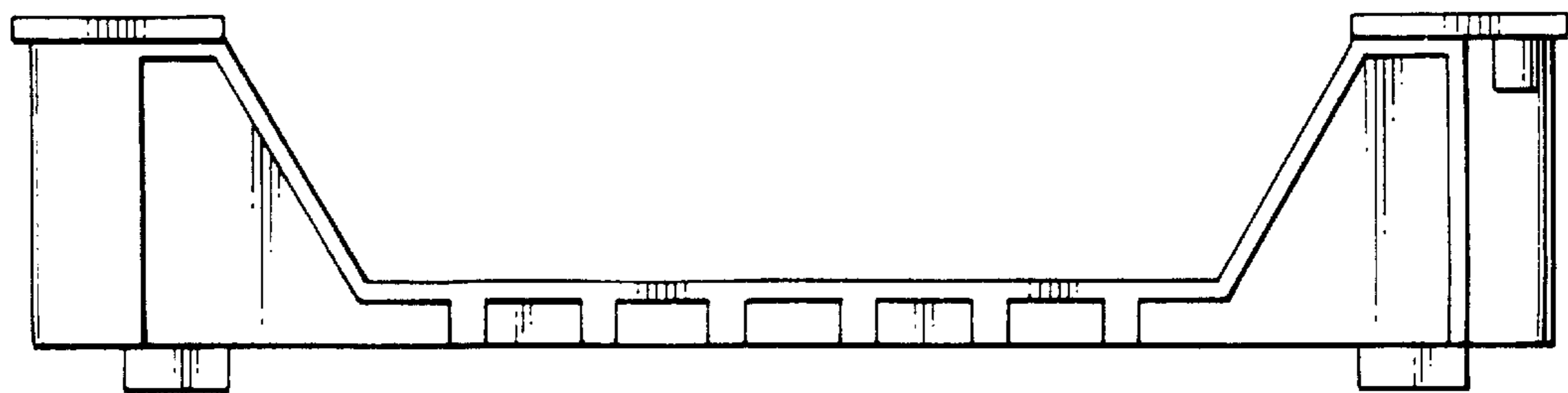


FIG. 13

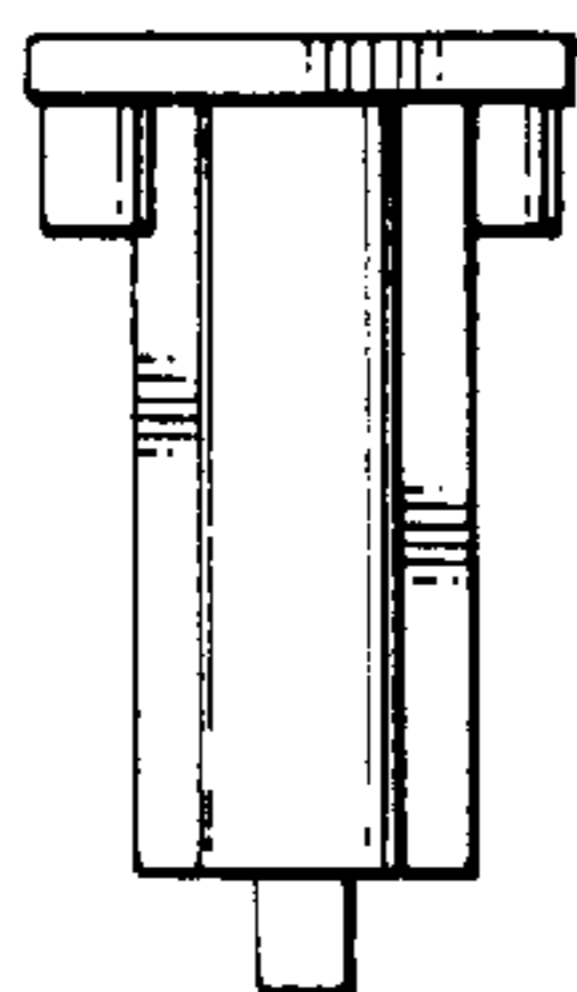


FIG. 14

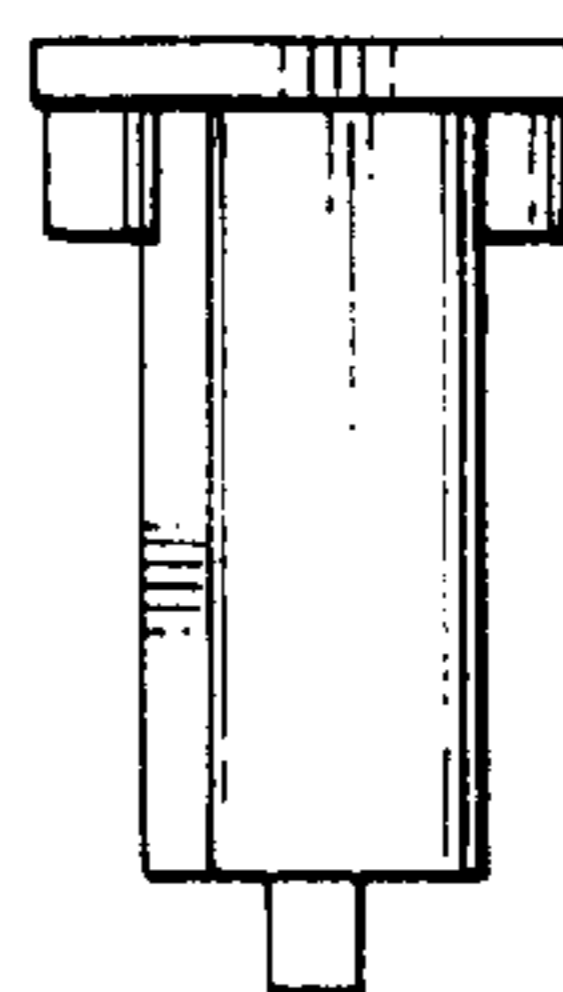


FIG. 15

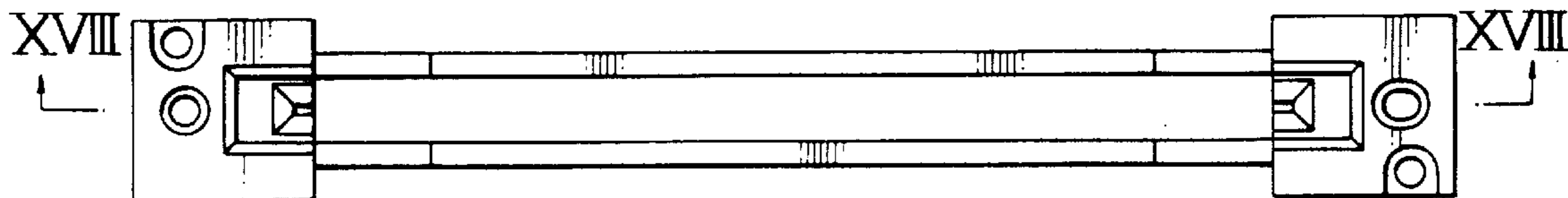


FIG. 16

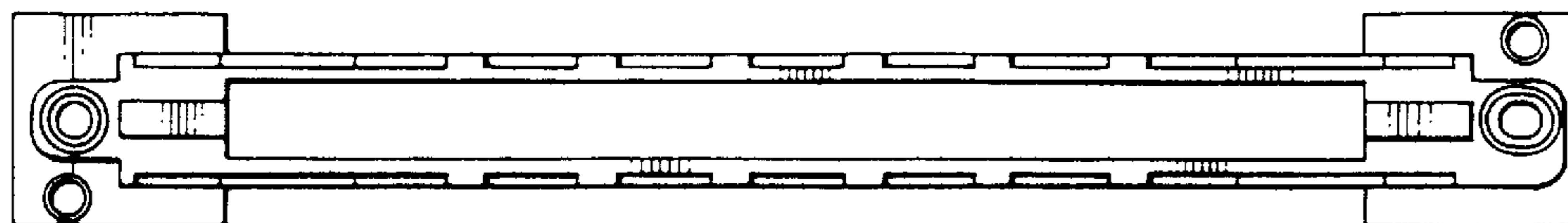


FIG. 17

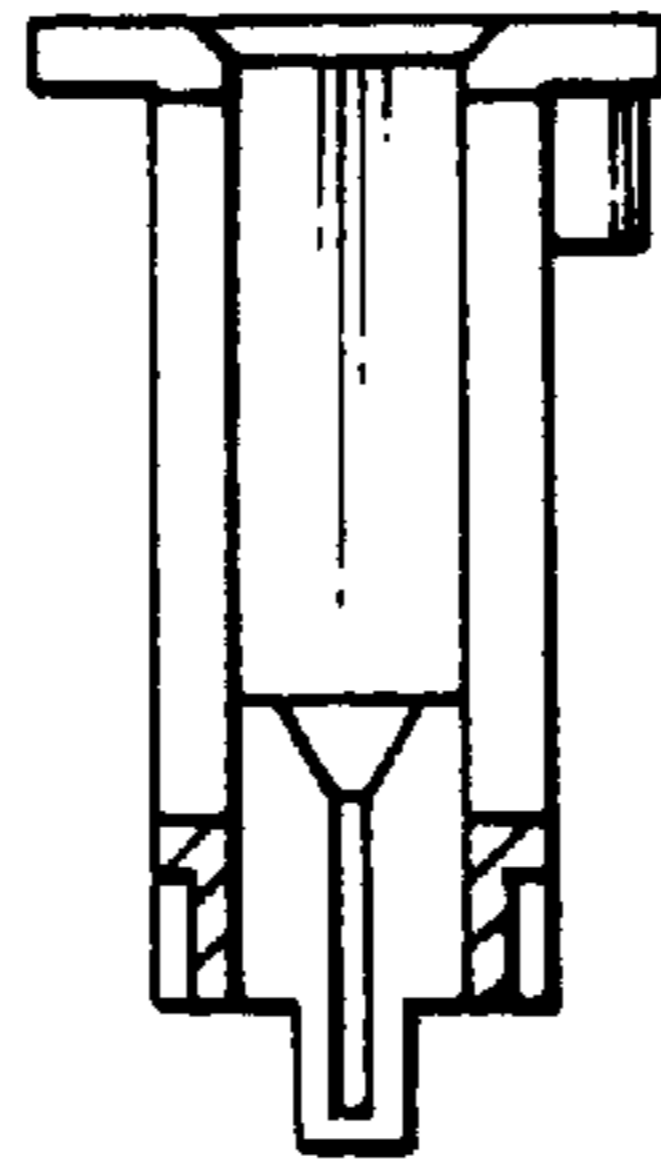


FIG. 18

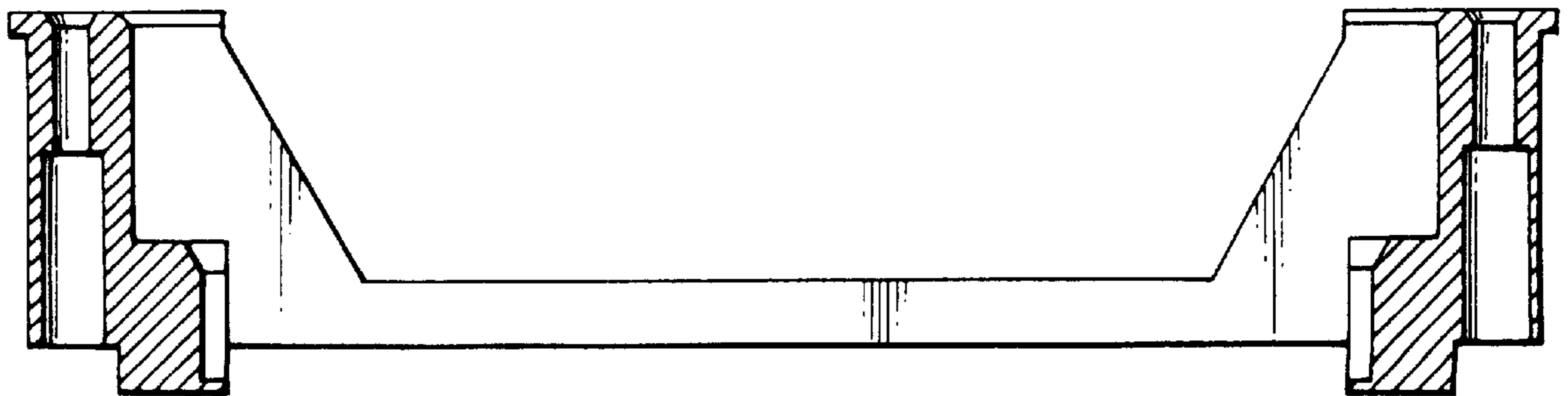


FIG. 19

